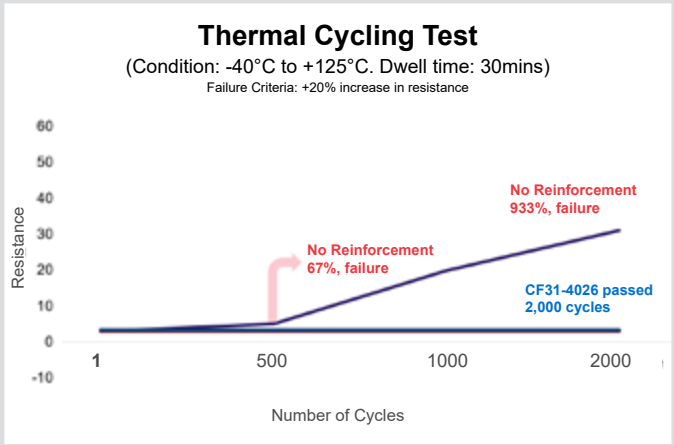
ALPHA® HiTech® CF31-4026

Next-Generation High Reliability Reworkable Edgebond

ALPHA HiTech CF31-4026 is a reworkable edgebond with high Tg and low CTE, purposefully engineered for high-temperature automotive applications that require exceptional board-level reliability. With superior thermal cycling performance and reworkability at temperatures as low as 185°C, this advanced edgebond offers improved process yields to help reach sustainability objectives.



Versatile in its applications, CF31-4026 extends its robust reinforcement to high reliability markets such as high-performance computing. This edgebond reinforces the BGA while avoiding contact with solder interconnects beneath the component. Its fluorescent appearance aids in efficient and accurate visual inspection. For industries that require both high temperature resilience and component reinforcement for extended operational life, ALPHA HiTech CF31-4026 is the optimal solution.

KEY ATTRIBUTES

- **Exceptional Bonding:** Provides strong adhesion to PCBs, ensuring reliability in critical applications.
- **Reworkable Design:** Removable at 185-200°C for high-yield manufacturing and lower total cost of ownership (TCO).
- **High Tg:** With a high glass transition temperature (Tg), this material is ideal for high-temperature applications.
- **Superior Slump Performance:** Prevents material from spreading to solder interconnects beneath components, maintaining integrity and reliability in high-density PCBs.
- **TCT Performance:** Low coefficient of thermal expansion (CTE) enhances thermal cycling performance and board-level reliability.
- **Fluorescent Appearance:** Facilitates prompt detection under UV in quality control processes.
- **Sustainability:** Halogen-free formulation promotes safer environmental practices, with a reworkable design that minimizes waste.

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